ON Semiconductor®

# Initial Product/Process Change Notification

Document # : IPCN22314Z1
Issue Date: 10 September 2018

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| **Title of Change:** | Update Notice - Cancellation of IPCN22314Z - Transfer of wafer fabrication operations for ON Semiconductor Zener products to ON Niigata, Japan. Change to AlSiCu top metal and Cu wire. | |
| **Proposed Changed Material First Ship Date:** | N/A | |
| **Current Material Last Order Date:** | N/A | |
| **Current Material Last Delivery Date:** | N/A | |
| **Product Category:** | Active components – Discrete components | |
| **Contact information:** | Contact your local ON Semiconductor Sales Office or <Hiroshi.Koizumi@onsemi.com> | |
| **Samples:** | Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com><br>Sample requests are to be submitted no later than 45 days after publication of this change notification. | |
| **Additional Reliability Data:** | Contact your local ON Semiconductor Sales Office or <Nicky.Siu@onsemi.com>. | |
| **Type of Notification:** | ON Semiconductor will consider this cancellation of change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>. | |
| **Change Category** | **Type of Change** | |
| Process – Wafer Production | New / change of metallization (specifically chip frontside)"<br>Move of all or part of wafer fab to a different location/site/subcontractor (qualification of an additional manufacturing site) | |
| Process – Assembly | Change of wire bonding | |

**Description and Purpose:**

This is an Update Notice for the Cancellation of IPCN22314Z - Transfer of wafer fabrication operations for ON Semiconductor Zener products to ON Niigata, Japan. Change to AlSiCu top metal and Cu wire.

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| **Reason / Motivation for Change:** | N/A | |
| **Anticipated impact on fit, form, function, reliability, product safety or manufacturability:** | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.<br><br>No anticipated impacts. | |
| **Sites Affected:** | ON Semiconductor Sites:<br>ON ISMF, Malaysia, ON Leshan, China,<br>ON Niigata, Japan | External Foundry/Subcon Sites:<br>None |
| **Marking of Parts/ Traceability of Change:** | N/A | |

**Reliability Data Summary:** N/A

**Electrical Characteristic Summary:** N/A

**List of Affected Parts:**

SZMM3Z43VT1G
SZMM3Z12VT1G